

ON Semiconductor®

FGD3245G2-F085 / FGB3245G2-F085 EcoSPARK[®]2 320mJ, 450V, N-Channel Ignition IGBT

Features

- SCIS Energy = 320mJ at T_J = 25°C
- Logic Level Gate Drive
- Low Saturation Voltage
- Qualified to AEC Q101
- RoHS Compliant

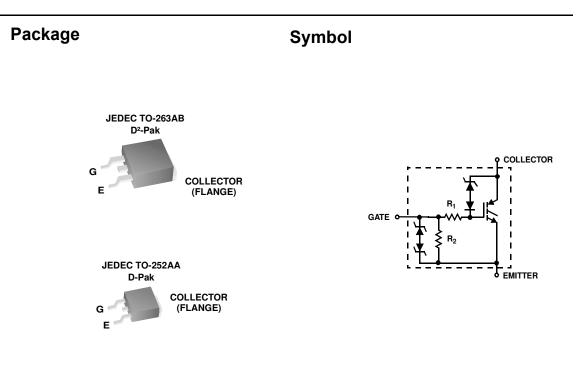
Applications

- Automotive Ignition Coil Driver Circuits
- Coil On Plug Applications

General Description

The FGB3245G2-F085 and FGD3245G2 are N-channel IGBTs designed in ON Semiconductor's EcoSPARK-2 technology which helps in eliminating external protection circuitry. The technology is optimized for driving the coil in the harsh environment of automotive ignition systems and offers out-standing Vsat and SCIS Energy capability also at elevated operating temperatures. The logic level gate input is ESD protected and features an integrated gate resistor. An inte-grated zener-circuitry clamps the IGBT's collecter- to-emit-ter voltage at 450V which enables systems requiring a higher spark voltage





Publication Order Number: FGD3245G2-F085/D

Symbol	Parameter	Rating	Units
BV _{CER}	Collector to Emitter Breakdown Voltage (I _C = 1mA)	450	V
BV _{ECS}	Emitter to Collector Voltage - Reverse Battery Condition (I _C = 10mA)	28	V
E _{SCIS25}	Self Clamping Inductive Switching Energy (Note 1)	320	mJ
E _{SCIS150}	Self Clamping Inductive Switching Energy (Note 2)	180	mJ
C25	Collector Current Continuous, at V _{GE} = 4.0V, T _C = 25°C	23	А
C110	Collector Current Continuous, at V _{GE} = 4.0V, T _C = 110°C	23	А
V _{GEM}	Gate to Emitter Voltage Continuous	±10	V
D	Power Dissipation Total, at T_{C} = 25°C	150	W
PD	Power Dissipation Derating, for T _C > 25°C	1.1	W/ºC
Г _Ј	Operating Junction Temperature Range	-40 to +175	°C
Г _{STG}	Storage Junction Temperature Range	-40 to +175	°C
ΓL	Max. Lead Temp. for Soldering (Leads at 1.6mm from case for 10s)	300	°C
Г _{РКG}	Max. Lead Temp. for Soldering (Package Body for 10s)	260	°C
ESD	Electrostatic Discharge Voltage at100pF, 1500 Ω	4	kV
130	CDM-Electrostatic Discharge Voltage at 1Ω	2	kV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGD3245G2	FGD3245G2-F085	TO252AA	330mm	16mm	2500 units
FGB3245G2	FGB3245G2-F085	TO263AB	330mm	24mm	800 units

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

	Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
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Off State Characteristics

BV _{CER}	Collector to Emitter Breakdown Voltage	$I_{CE} = 2mA, V_{GE} = 0,$ $R_{GE} = 1K\Omega,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$		420	-	480	v
BV _{CES}	Collector to Emitter Breakdown Voltage	$I_{CE} = 10mA, V_{GE} = 0V,$ $R_{GE} = 0,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$		440	-	500	V
BV _{ECS}	Emitter to Collector Breakdown Voltage	I _{CE} = -75mA, V _{GE} = 0V, T _J = 25°C		28	-	-	V
BV _{GES}	Gate to Emitter Breakdown Voltage	I _{GES} = ±2mA		±12	±14	-	V
1	Collector to Emitter Leakage Current	V _{CE} = 250V, R _{GE} = 1KΩ	T _J = 25 ^o C	-	-	25	μA
ICER			T _J = 150 ^o C	-	-	1	mA
	Emitter to Collector Leakage Current	V _{EC} = 24V,	T _J = 25°C	-	-	1	mA
IECS			T _J = 150 ^o C	-	-	40	ШA
R ₁	Series Gate Resistance			-	120	-	Ω
R ₂	Gate to Emitter Resistance			10K	-	30K	Ω

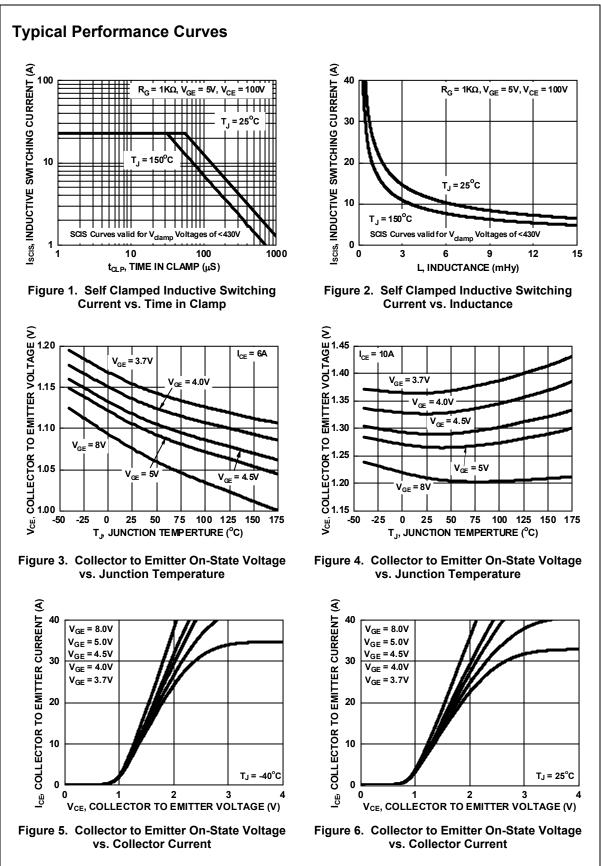
On State Characteristics

V _{CE(SAT}	Collector to Emitter Saturation Voltage	$I_{CE} = 6A, V_{GE} = 4V,$	$T_J = 25^{\circ}C$	-	1.13	1.25	V
V _{CE(SAT}	Collector to Emitter Saturation Voltage	I _{CE} = 10A, V _{GE} = 4.5V,	T _J = 150 ^o C	-	1.32	1.50	V
V _{CE(SAT}	Collector to Emitter Saturation Voltage	$I_{CE} = 15A, V_{GE} = 4.5V,$	T _J = 150 ^o C	-	1.64	1.85	V

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Dynam	ic Characteristics						
Q _{G(ON)}	Gate Charge	I _{CE} = 10A, V _{CE} = 12V, V _{GE} = 5V		-	23	-	nC
	Gate to Emitter Threshold Voltage	I _{CE} = 1mA, V _{CE} = V _{GE}	$T_J = 25^{\circ}C$	1.3	1.6	2.2	v
V _{GE(TH)}	Gale to Emilier Threshold Voltage	CE = TTTA, VCE = VGE,	T _J = 150 ^o C	0.75	1.1	1.8	v
V _{GEP}	Gate to Emitter Plateau Voltage	V _{CE} = 12V, I _{CE} = 10A		-	2.7	-	V
t _{d(ON)R}	ing Characteristics Current Turn-On Delay Time-Resistive			-	0.9	4	μS
t _{rR}	Current Rise Time-Resistive	V _{GE} = 5V, R _G = 1KΩ T _{.1} = 25°C,		-	2.6	7	μS
d(OFF)L	Current Turn-Off Delay Time-Inductive	02		-	5.4	15	μS
	Current Fall Time-Inductive	V _{GE} = 5V, R _G = 1KΩ I _{CE} = 6.5A, T _J = 25 ^o C,		-	2.7	15	μS
t _{fL}		$L = 3.0 \text{ mHy}, RG = 1K\Omega$,					

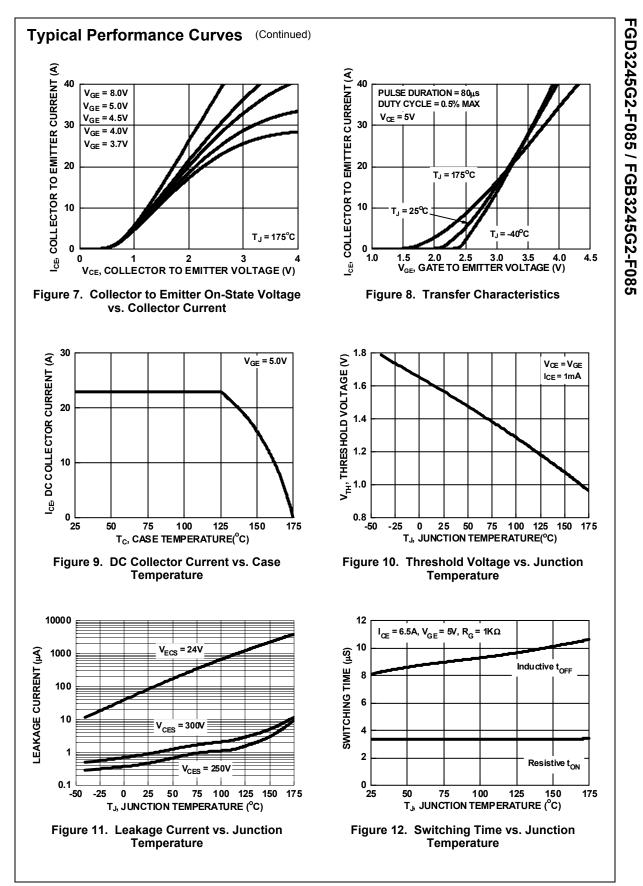
Notes:

1: Self Clamping Inductive Switching Energy (E_{SCIS25}) of 320 mJ is based on the test conditions that starting Tj=25^oC; L=3mHy, I_{SCIS}=14.6A,V_{CC}=100V during inductor charging and V_{CC}=0V during the time in clamp. 2: Self Clamping Inductive Switching Energy ($E_{SCIS150}$) of 180 mJ is based on the test conditions that starting Tj=150^oC; L=3mHy, I_{SCIS}=10.9A,V_{CC}=100V during inductor charging and V_{CC}=0V during the time in clamp.

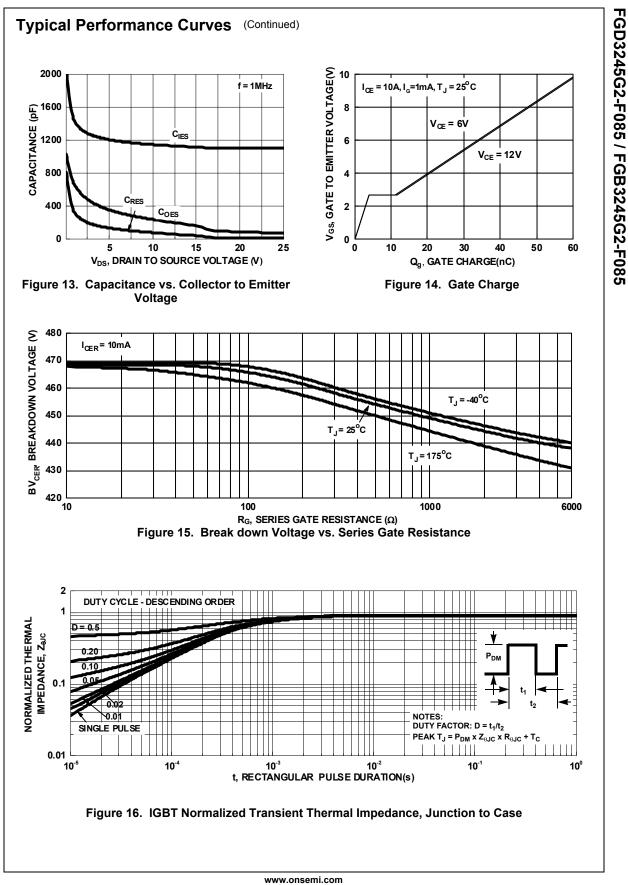


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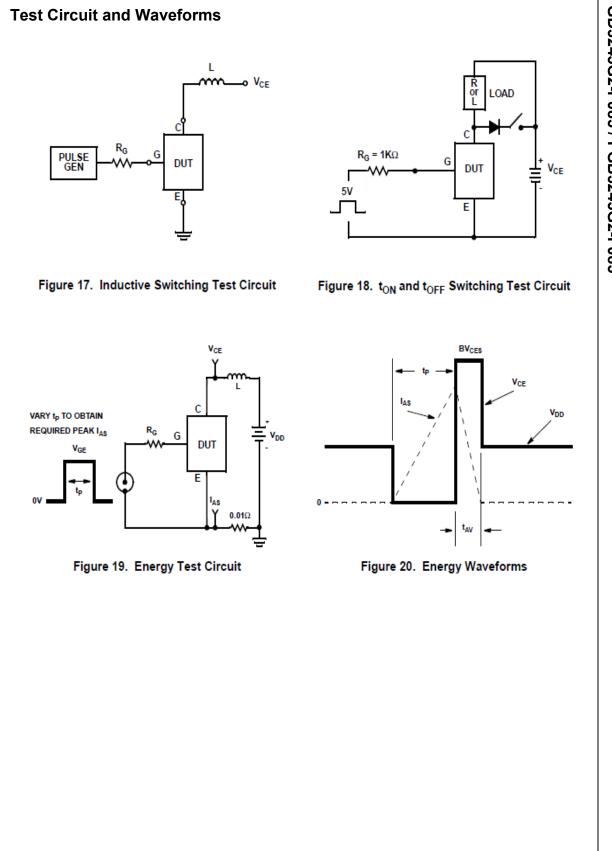




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